1. General description

Low leakage current Schottky barrier rectifier encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low forward voltage
- Low leakage current
- · High thermal stability and large Safe Operation Area
- · High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- · Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- High efficiency DC-to-DC conversion
- · Automotive LED lighting
- Switch mode power supply
- · Freewheeling application
- · Reverse polarity protection
- OR-ing

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} \leq 170 °C		-	-	6	А
V _R	reverse voltage	T _j = 25 °C		-	-	100	V
V _F	forward voltage	I _F = 6 A; pulsed; T _j = 25 °C	[1]	-	770	840	mV
I _R	reverse current	V _R = 100 V; pulsed; T _j = 25 °C	[1]	-	0.1	0.45	μΑ
		V _R = 100 V; pulsed; T _j = 125 °C	[1]	-	0.2	0.8	mA

^[1] Very short pulse, in order to maintain a stable junction temperature.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode	5	
2	Α	anode		K A
3	K	cathode	2	aaa-009063
			CFP15B (SOT1289B)	

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG100V060ELPE-Q		plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	<u>SOT1289B</u>

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG100V060ELPE-Q	100V L06E

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	100	V
I _F	forward current	δ = 1; $T_{sp} \le 169 ^{\circ}\text{C}$		-	8.4	Α
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; T _{sp} ≤ 170 °C		-	6	А
I _{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; square wave; $T_{j(init)}$ = 25 °C		-	130	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
Tj	junction temperature			-	175	°C
T _{amb}	ambient temperature			-55	175	°C
T _{stg}	storage temperature			-65	175	°C

^[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

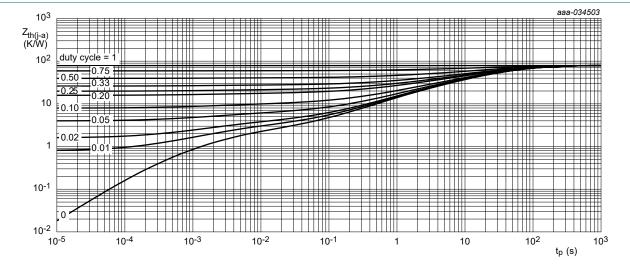
^[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

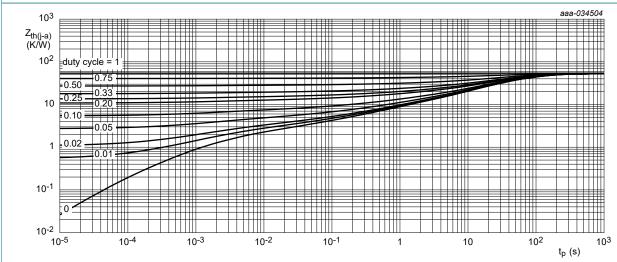
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from	in free air	[1] [2]	-	-	90	K/W
junction to ambient		[1] [3]	-	-	70	K/W	
R _{th(j-sp)}	thermal resistance from junction to solder point		[4]	-	-	3	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

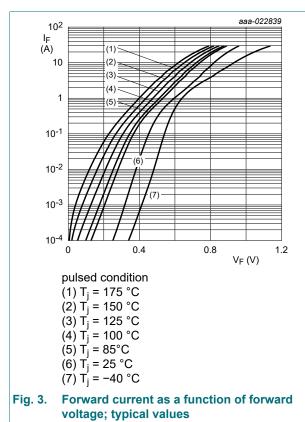
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

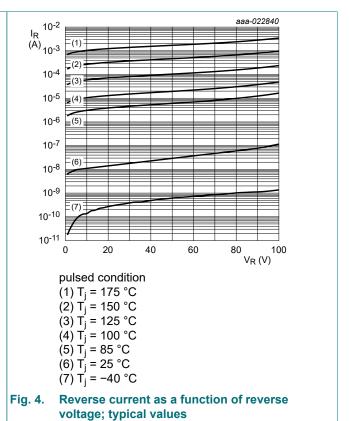
10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	I_R = 1 mA; pulsed; T_j = 25 °C	[1]	100	-	-	V
V _F	forward voltage	I _F = 1 A; pulsed; T _j = 25 °C	[1]	-	600	670	mV
		I _F = 3 A; pulsed; T _j = 25 °C	[1]	-	710	770	mV
		I _F = 6 A; pulsed; T _j = 25 °C	[1]	-	770	840	mV
		I _F = 6 A; pulsed; T _j = -40 °C	[1]	-	860	970	mV
		I _F = 6 A; pulsed; T _j = 125 °C	[1]	-	630	750	mV
I _R	reverse current	V _R = 100 V; pulsed; T _j = 25 °C	[1]	-	0.1	0.45	μΑ
		V _R = 100 V; pulsed; T _j = 125 °C	[1]	-	0.2	0.8	mA
		V _R = 100 V; pulsed; T _j = 150 °C	[1]	-	1	4.5	mA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C		-	175	-	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C		-	73	-	pF
t _{rr}	reverse recovery time	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$		-	8	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	565	-	mV

[1] Very short pulse, in order to maintain a stable junction temperature.





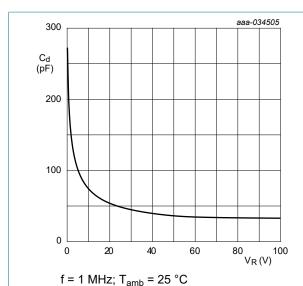
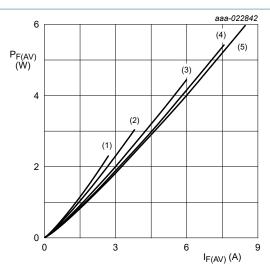
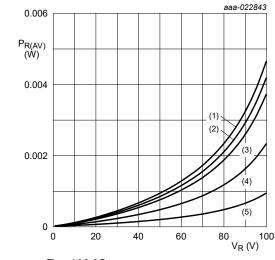


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



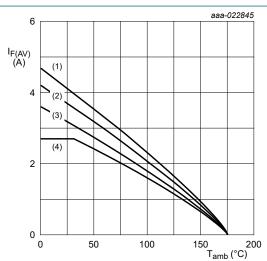
 $T_j = 100 \,^{\circ}\text{C}$ $(1) \, \delta = 0.1$ $(2) \, \delta = 0.2$ $(3) \, \delta = 0.5$ $(4) \, \delta = 0.8$ $(5) \, \delta = 1$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_j = 100 \,^{\circ}\text{C}$ $(1) \, \delta = 1$ $(2) \, \delta = 0.9$ $(3) \, \delta = 0.8$ $(4) \, \delta = 0.5$ $(5) \, \delta = 0.2$

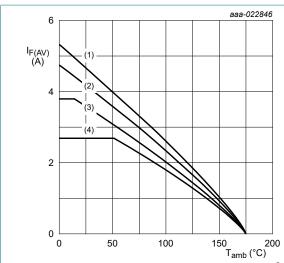
Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint $T_j = 175$ °C (1) $\delta = 1$; DC (2) $\delta = 0.5$; f = 20 kHz (3) $\delta = 0.2$; f = 20 kHz (4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values

5 / 13



FR4 PCB, mounting pad for cathode 1 cm²

 $T_i = 175 \,{}^{\circ}\text{C}$

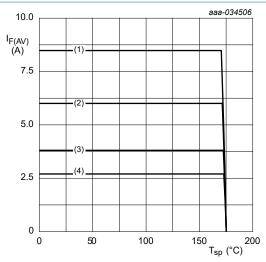
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



Ti = 175 °C

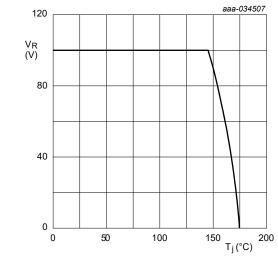
(1) δ = 1; DC

(2) δ = 0.5; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

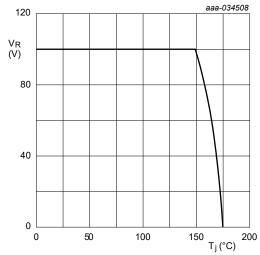
Fig. 10. Average forward current as a function of solder point temperature; typical values



FR4 PCB, standard footprint

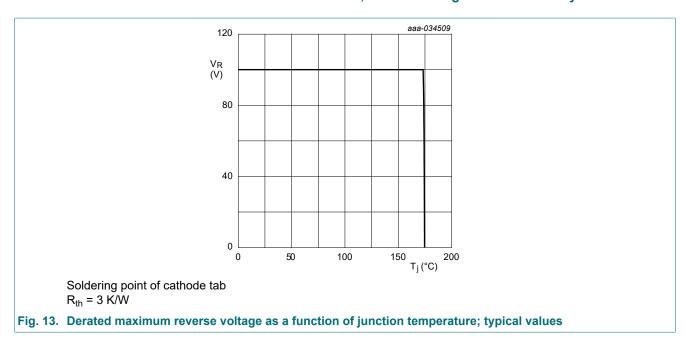
 $R_{th} = 90 \text{ K/W}$

of junction temperature; typical values

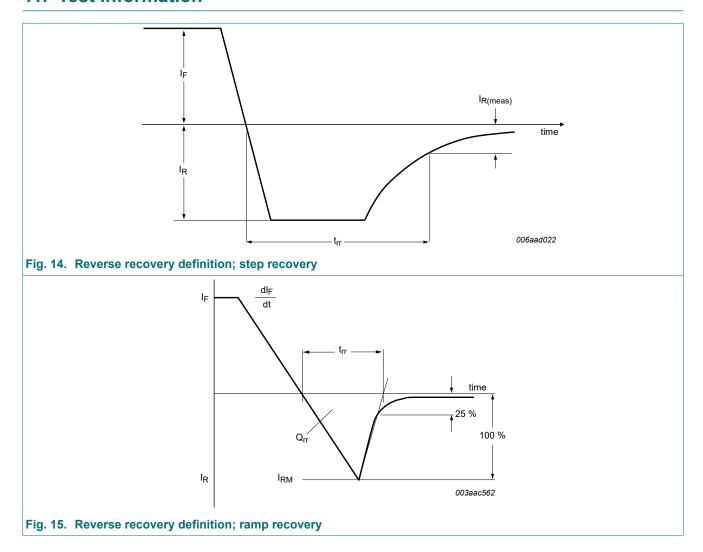


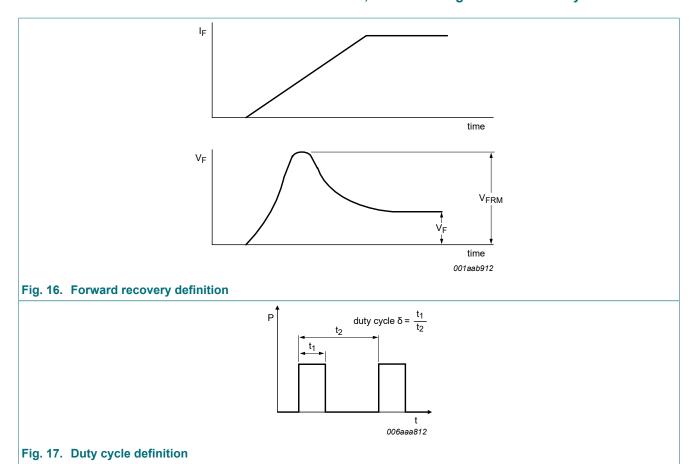
FR4 PCB, mounting pad for cathode 1 cm² $R_{th} = 70 \text{ K/W}$

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



11. Test information





The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

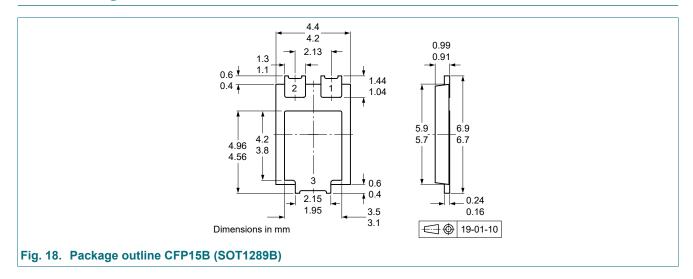
 $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_{M} \times \sqrt{\delta}$

with $I_{\mbox{\scriptsize RMS}}$ defined as RMS current.

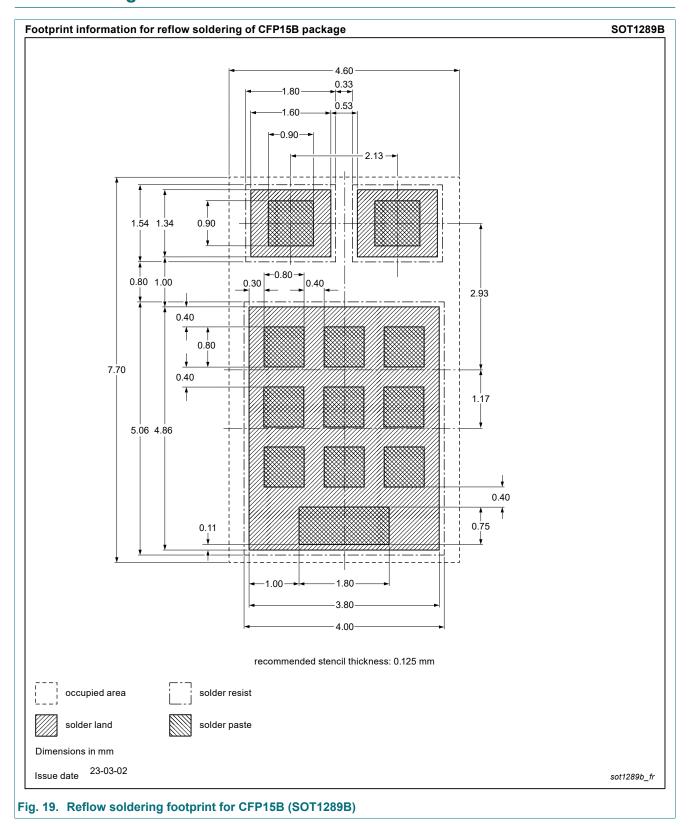
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline



13. Soldering



14. Revision history

Table 8. Revision history

Table of Nevicion motory								
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes				
PMEG100V060ELPE-Q v.3	20240715	Product data sheet	-	PMEG100V060ELPE-Q v.2				
Modifications:	 Limiting values: Conditions changed at I_{F(AV)} Reflow soldering footprint: Stencil design for solder paste printing changed. 							
PMEG100V060ELPE-Q v.2	20220715	Product data sheet	-	PMEG100V060ELPE-Q v.1				
PMEG100V060ELPE-Q v.1	20220302	Preliminary data sheet	-	-				

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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